2SD2136

Silicon NPN triple diffusion planar type

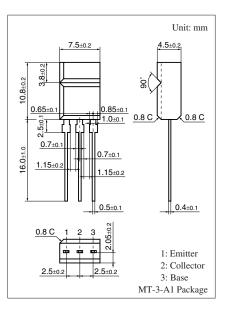
For power amplification Complementary to 2SB1416

Features

- \bullet High forward current transfer ratio $h_{F\!E}$ which has satisfactory linearity.
- Low collector-emitter saturation voltage $V_{CE(sat)}$
- Allowing supply with the radial taping

Parameter	Symbol	Rating	Unit			
Collector-base voltage (Emitter open)	V _{CBO}	60	V			
Collector-emitter voltage (Base open)	V _{CEO}	60	V			
Emitter-base voltage (Collector open)	V _{EBO}	6	V			
Collector current	I _C	3	А			
Peak collector current	I _{CP}	5	А			
Collector power dissipation	P _C	1.5	W			
Junction temperature	Tj	150	°C			
Storage temperature	T _{stg}	-55 to +150	°C			





Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 30 \text{ mA}, I_{\rm B} = 0$	60			V
Base-emitter voltage *1	V _{BE}	$V_{CE} = 4 V, I_C = 3 A$			1.8	V
Collector-emitter cutoff current (Emitter-base short)	I _{CES}	$V_{CE} = 60 \text{ V}, V_{BE} = 0$			200	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = 30 \text{ V}, I_B = 0$			300	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = 6 V, I_C = 0$			1	mA
Forward current transfer ratio	h _{FE1} *2	$V_{CE} = 4 V, I_C = 1 A$	40		250	_
	h _{FE2} *1	$V_{CE} = 4 V, I_C = 3 A$	10			
Collector-emitter saturation voltage *1	V _{CE(sat)}	$I_{\rm C} = 3$ A, $I_{\rm B} = 0.375$ A			1.2	V
Transition frequency	f _T	$V_{CE} = 5 \text{ V}, I_E = -0.1 \text{ A}, f = 200 \text{ MHz}$		220		MHz
Turn-on time	t _{on}	$I_C = 1 A, I_{B1} = 0.1 A, I_{B2} = -0.1 A$		0.5		μs
Storage time	t _{stg}			2.5		μs
Fall time	t _f			0.4		μs

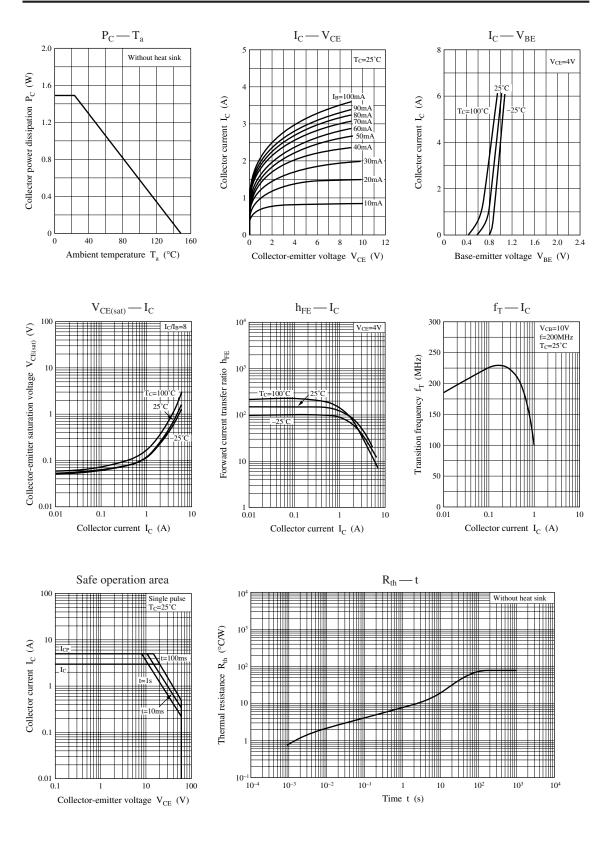
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *1: Pulse measurement

*2: Rank classification

Rank	Р	Q	R
h _{FE1}	40 to 90	70 to 150	120 to 250

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